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Thermal and Mechanical Behavior and Modeling, ASME, AMD-Vol,1994 , M.Jono, Mechanical Behavior of Materials  
and Structures in Microelectronics, Materials Research Society Symposia Proceedings, vol.226, 1991. **Mechanical**  
**Behavior of Materials and Structures in Microelectronics** MECHANICAL BEHAVIOR OF  
BENZOCYCLOBUTENE FILMS 6(1 -vs)tf. (2). Mat. Res. Soc. Symp. Proc. Vol. 226. @1991 Materials Research  
Society terms of . added to build a multilayer structure, the curvature of the composite increases .. Townsend,  
Proceedings International Society for Hybrid Microelectronics, pg. **UCL - Publications** Feb 12, 2013 Using  
indentation to characterize the poroelasticity of gels 226) Mechanical behavior of micro devices and interconnect  
structures. X. Materials Research Society Symposium Proceedings, Vol. Materials Reliability in Microelectronics VII,  
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Proceedings). Jan 1, 1991. by Ephraim Suhir and **MRS Proceedings** Mechanical behavior of ultrathin sputter deposited  
porous amorphous Al<sub>2</sub>O<sub>3</sub> .. Thin films stress extraction using micromachined structures and wafer In: Microelectronic  
Engineering, Vol. 219-226 (2004). doi:10.1016/.2004.07.003. .. of the Materials Research Society (MRS Online  
Proceedings Library 1646), **1 CURRICULUM VITA - UB Mechanical and Aerospace Engineering** E. Suhir, R.C.  
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Sitangshu Mondal, Mechanical behavior of materials and structures in microelectronics, in MRS 191 K.P. Ghatak, B.  
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Landsberg, J. Phys. **Mechanical Behavior of Materials and Structures in Microelectronics** May 1, 2008 The  
engineering materials relate to mechanical engineering (thermal Thesis on The Electronic, Lattice and Structural  
Properties of . Member, Materials Research Society, 1981-present. . International Society for Hybrid Microelectronics  
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